[0031] each of n_1 and n_2 independently is an integer of 1 to 6.

[0032] [2] The composition according to the above item [1], wherein the organic group is an alkyl group or an aryl group.

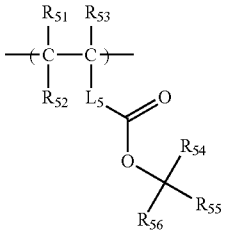
[0033] [3] The composition according to the above item [1] or [2], wherein the compound (R) is expressed by general formula (1), and wherein at least one of R_4 and R_7 is a hydrogen atom.

[0034] [4] The composition according to the above item [3], wherein both of R_4 and R_7 are hydrogen atoms.

[0035] [5] The composition according to the above item [1] or [2], wherein the compound (R) is expressed by general formula (2), and wherein R_7 is a hydrogen atom.

[0036] [6] The composition according to any of the above items [1] to [5], wherein the repeating unit (A) is expressed by general formula (V) or (VI) below.

(V)

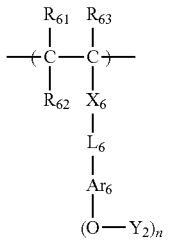


[0037] In general formula (V), each of R_{51}, R_{52} and R_{53} independently represents a hydrogen atom, an alkyl group, a cycloalkyl group, a halogen atom, a cyano group or an alkoxycarbonyl group, provided that R_{52} may be bonded to L_5 to thereby form a ring, which R_{52} represents an alkylene group,

[0038] L_5 represents a single bond or a bivalent connecting group, provided that when a ring is formed in cooperation with R_{52}, L_5 represents a trivalent connecting group, and

[0039] R_{54} represents an alkyl group, and each of R_{55} and R_{56} independently represents a hydrogen atom, an alkyl group, a cycloalkyl group or a monovalent aromatic ring group, provided that R_{55} and R_{56} may be bonded to each other to thereby form a ring, and provided that R_{55} and R_{56} are not simultaneously hydrogen atoms.

(VI)



[0040] In general formula (VI), each of R_{61}, R_{62} and R_{63} independently represents a hydrogen atom, an alkyl group, a cycloalkyl group, a halogen atom, a cyano group or an alkoxycarbonyl group, provided that R_{62} may be bonded to Ar_6 to thereby form a ring, which R_{62} represents an alkylene group,

[0041] X_6 represents a single bond, —COO— or —$CONR_{64}$— in which R_{64} represents a hydrogen atom or an alkyl group,

[0042] L_6 represents a single bond or an alkylene group,

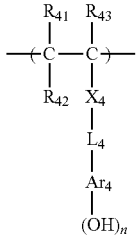
[0043] Ar_6 represents a bivalent aromatic ring group,

[0044] Y_2, when n≥2 each independently, represents a hydrogen atom or a group that when acted on by an acid, is cleaved, provided that at least one of Y_2s is a group that when acted on by an acid, is cleaved, and

[0045] n is an integer of 1 to 4.

[0046] [7] The composition according to any of the above items [1] to [6], wherein the resin (P) further contains any of repeating units (B) expressed by general formula (I) below.

(I)



[0047] In general formula (I), each of R_{41}, R_{42} and R_{43} independently represents a hydrogen atom, an alkyl group, a halogen atom, a cyano group or an alkoxycarbonyl group,

[0048] X_4 represents a single bond, —COO— or —$CONR_{64}$— in which R_{64} represents a hydrogen atom or an alkyl group,

[0049] L_4 represents a single bond or an alkylene group,

[0050] Ar_4 represents a (n+1)-valent aromatic ring group, and

[0051] n is an integer of 1 to 4.

[0052] [8] The composition according to the above item [7], wherein the repeating unit (B) has a hydroxystyrene structure.

[0053] [9] The composition according to any of the above items [1] to [8], further comprising a basic compound other than the compound (R).

[0054] [10] The composition according to the above item [9], wherein the basic compound contains no hydroxyl group.

[0055] [11] The composition according to any of the above items [1] to [10] for use in a pattern formation including exposure by EUV.

[0056] [12] An actinic-ray- or radiation-sensitive resin film formed from the composition according to any of the above items [1] to [11].

[0057] [13] A method of forming a pattern, comprising:

[0058] exposing the film according to the above item [12] to light, and

[0059] developing the exposed film.

[0060] [14] The method according to item [13], wherein the exposure is carried out by EUV light.

[0061] [15] A process for manufacturing an electronic device, comprising the pattern forming method according to the above item [13] or [14].

[0062] [16] An electronic device manufactured by the process according to the above item [15].

[0063] The present invention has made it feasible to provide an actinic-ray- or radiation-sensitive resin composition that can attain high sensitivity, favorable pattern shape, favor-